

### T-1 3/4 (5mm) BI-COLOR RIGHT ANGLE LED **INDICATOR**

Part Number: WP150A9VS/EYW

High Efficiency Red

Yellow

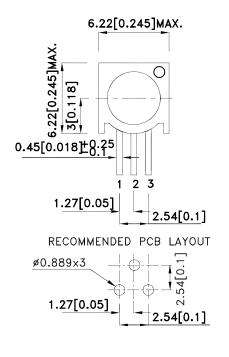
#### **Features**

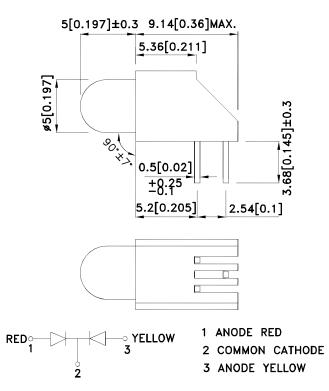
- Pre-trimmed leads for pc board mounting.
- High reliability life measured in years.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

### **Descriptions**

- The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.
- The Yellow source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Yellow Light Emitting Diode.

## **Package Dimensions**





- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25(0.01") unless otherwise noted.
- Lead spacing is measured where the leads emerge from the package.
   The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

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### **Selection Guide**

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
WP150A9VS/EYW	High Efficiency Red (GaAsP/GaP)	White Diffused	18	50	30°
			*12	*30	
	Yellow (GaAsP/GaP)		8	20	
			*8	*20	

- Notes:
  1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
  2. Luminous intensity/ luminous Flux: +/-15%.

  \* Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

## Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red Yellow	627 590		nm	Ir=20mA
λD [1]	Dominant Wavelength	High Efficiency Red Yellow	617 588		nm	I==20mA
Δλ1/2	Spectral Line Half-width	High Efficiency Red Yellow	45 35		nm	I==20mA
С	Capacitance	High Efficiency Red Yellow	15 20		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	High Efficiency Red Yellow	2 2.1	2.5 2.5	V	I==20mA
lR	Reverse Current	High Efficiency Red Yellow		10 10	uA	VR = 5V

### Notes:

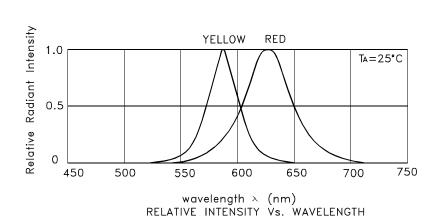
- 1.Wavelength: +/-1nm.
- 2.Forward Voltage: +/-0.1V.
- 3. Wavelength value is traceable to the CIE127-2007 compliant national standards.
- 4. Excess driving current and/or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

# Absolute Maximum Ratings at TA=25°C

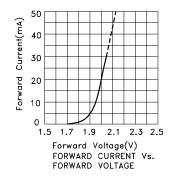
Parameter	High Efficiency Red	ency Red Yellow			
Power dissipation	75	75	mW		
DC Forward Current	30	30	mA		
Peak Forward Current [1]	160	140	mA		
Reverse Voltage	5 V				
Operating / Storage Temperature	-40°C To +85°C				
Lead Solder Temperature [2]	260°C For 3 Seconds				
Lead Solder Temperature [3]	260°C For 5 Seconds				

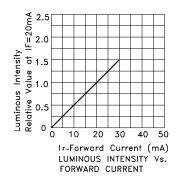
- 1. 1/10 Duty Cycle, 0.1ms Pulse Width.
- 2. 2mm below package base.
- 3. 5mm below package base.

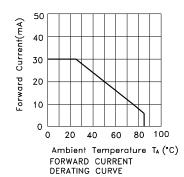
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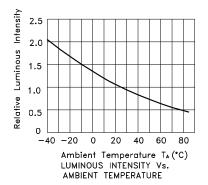


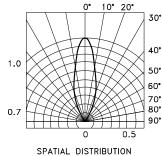
# WP150A9VS/EYW High Efficiency Red







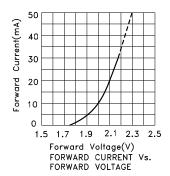


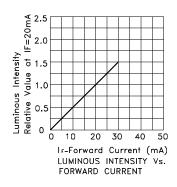


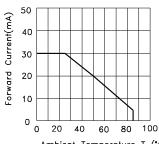
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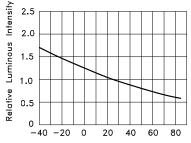
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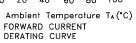
## Yellow



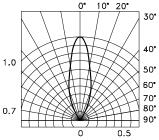








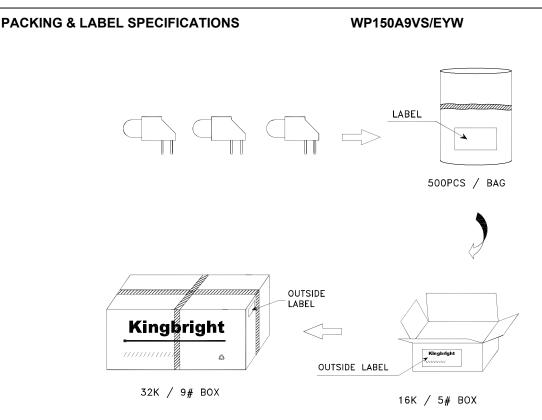
Ambient Temperature T<sub>A</sub> (°C) LUMINOUS INTENSITY Vs. AMBIENT TEMPERATURE



SPATIAL DISTRIBUTION

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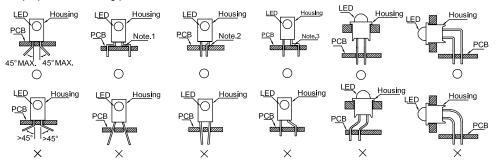
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#### **PRECAUTIONS**

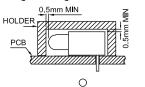
- 1. Storage conditions:
  - a. Avoid continued exposure to the condensing moisture environment and keep the product away from rapid transitions in ambient temperature.
  - b.LEDs should be stored with temperature ≤30°C and relative humidity < 60%.
  - c.Product in the original sealed package is recommended to be assembled within 72 hours of opening. Product in opened package for more than a week should be baked for 30 ( $\pm$ 10/-0) hours at 85 ~ 100°C.
- The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.

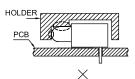


"  $\bigcirc$  " Correct mounting method " imes " Incorrect mounting method

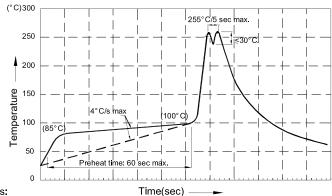
Note 1-3: Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

3. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.





- 4. The tip of the soldering iron should never touch the lens epoxy.
- 5. Through-hole LEDs are incompatible with reflow soldering.
- 6. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.
- 7. Recommended Wave Soldering Profiles:



- Notes: Time(sec) — 1.Recommend pre-heat temperature of 105° C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260° C
- 2.Peak wave soldering temperature between 245° C ~ 255° C for 3 sec (5 sec max).
- 3.Do not apply stress to the epoxy resin while the temperature is above 85°C.
- 4. Fixtures should not incur stress on the component when mounting and during soldering process.
- 5.SAC 305 solder alloy is recommended.
- 6.No more than one wave soldering pass.

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